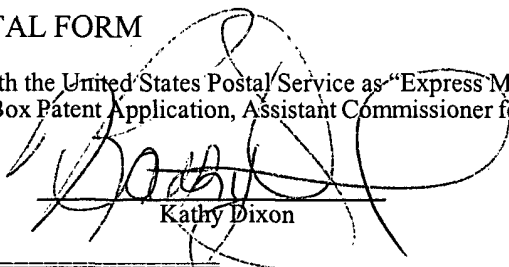




TRANSMITTAL FORM

I hereby certify that this correspondence is being deposited with the United States Postal Service as "Express Mail" under label No. EV 261 231 025 US in an envelope addressed to: Box Patent Application, Assistant Commissioner for Patents, Washington, D.C. 20231 on:

June 18, 2003
(Date of Deposit)


Kathy Dixon



Box Patent Application
Assistant Commissioner
For Patents
Washington, D.C. 20231

Attorney Doc. #: 68,700-015
Mailing Date: June 18, 2003

Dear Sir:

Transmitted herewith for filing is the patent application of:

Inventor(s): Kuo-Lung Lei

For: MEMS MICRO-CAP WAFER LEVEL CHIP SCALE PACKAGE

Submitted herewith are:

- X 2 sheet(s) of formal drawings
X An Assignment of the invention to Aptos Corporation, together with Assignment Recordal Sheet
X A Declaration for patent application under CFR 1.63 and 1.68

The filing fee has been calculated as shown below:

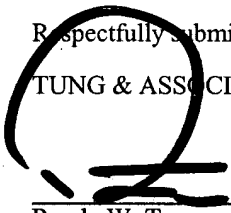
	No. Filed	No. Extra	Small Entity Fee	Large Entity Fee	Total
Basic Fee			\$375.00	\$750.00	\$375.00
Total Claims	25x20	5 x	\$9.00	\$18.00	\$45.00
Indep. Claims	3-3	0 x	\$42.00	\$84.00	\$0
Multiple Dep. Clms.			\$140.00	\$280.00	\$0
Assign. Rec. Fee			\$40.00	\$40.00	\$40.00
TOTAL					\$460.00

Mailing Date: June 18, 2003
Attorney Docket No.: 68,700-015

- ☒ Attached is a Credit Card Payment Form for the sum of \$ 460.00
- ☒ Charge Visa Credit Card No. [REDACTED] the sum of \$ 460.00
A duplicate copy of this transmittal is attached.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Visa Credit Card No. [REDACTED].
A duplicate copy of this sheet is enclosed.
- ☒ Any additional filing fees required under 37 CFR 1.6
☒ Any patent application processing fees under 37 CFR 1.17

Respectfully submitted,

TUNG & ASSOCIATES



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RWT/kd
Enclosures